

BAW56LT1G, SBAW56LT1G, BAW56LT3G, SBAW56LT3G, SSV1BAW56LT1G



ON Semiconductor®

<http://onsemi.com>

Dual Switching Diode Common Anode

Features

- AEC-Q101 Qualified and PPAP Capable
- S & SSV1 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant*

MAXIMUM RATINGS (EACH DIODE)

| Rating | Symbol | Value | Unit |
|---|-----------------|-------|------|
| Reverse Voltage | V_R | 70 | V |
| Forward Current | I_F | 200 | mA |
| Peak Forward Surge Current | $I_{FM(surge)}$ | 500 | mA |
| Non-Repetitive Peak Forward Current $t = 1 \mu s$ (Note 3) | I_{FSM} | 4 | A |

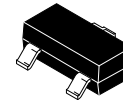
THERMAL CHARACTERISTICS

| Characteristic | Symbol | Max | Unit |
|--|-----------------|----------------|----------------|
| Total Device Dissipation FR-5 Board (Note 1) $T_A = 25^\circ C$ Derate above $25^\circ C$ | P_D | 225 | mW |
| | | 1.8 | mW/ $^\circ C$ |
| Thermal Resistance, Junction-to-Ambient | $R_{\theta JA}$ | 556 | $^\circ C/W$ |
| Total Device Dissipation Alumina Substrate, (Note 2) $T_A = 25^\circ C$ Derate above $25^\circ C$ | P_D | 300 | mW |
| | | 2.4 | mW/ $^\circ C$ |
| Thermal Resistance, Junction-to-Ambient | $R_{\theta JA}$ | 417 | $^\circ C/W$ |
| Junction and Storage Temperature | T_J, T_{stg} | -55 to +150 | $^\circ C$ |

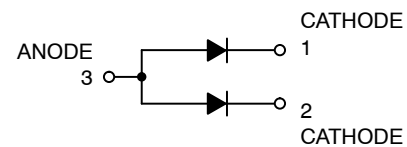
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR-5 = $1.0 \times 0.75 \times 0.062$ in.
2. Alumina = $0.4 \times 0.3 \times 0.024$ in. 99.5% alumina.
3. Square Wave; $T_J = 25^\circ C$.

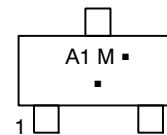
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



SOT-23 (TO-236)
CASE 318
STYLE 12



MARKING DIAGRAM



A1 = Device Code
M = Date Code*
▪ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

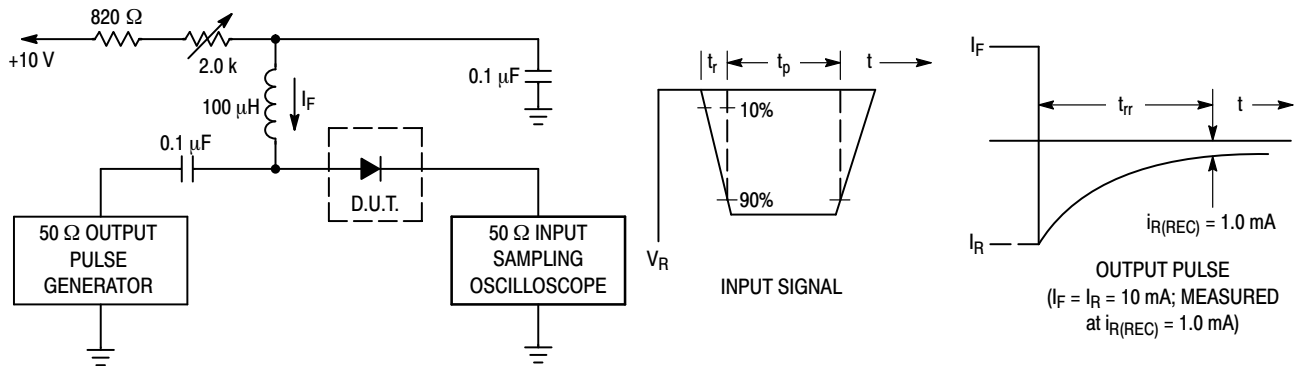
| Device | Package | Shipping [†] |
|---------------|---------------------|-------------------------|
| BAW56LT1G | SOT-23 (Pb-Free) | 3,000 / Tape & Reel |
| SBAW56LT1G | SOT-23 (Pb-Free) | 3,000 / Tape & Reel |
| BAW56LT3G | SOT-23 (Pb-Free) | 10,000 / Tape & Reel |
| SBAW56LT3G | SOT-23 (Pb-Free) | 10,000 / Tape & Reel |
| SSV1BAW56LT1G | SOT-23 (Pb-Free) | 3,000 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted) (Each Diode)

| Characteristic | Symbol | Min | Max | Unit |
|---|------------|-----|----------------------------|---------------|
| Reverse Breakdown Voltage ($I_{(BR)} = 100 \mu\text{A}$) | $V_{(BR)}$ | 70 | - | V |
| Reverse Voltage Leakage Current ($V_R = 25 \text{ V}, T_J = 150^\circ\text{C}$) ($V_R = 70 \text{ V}$) ($V_R = 70 \text{ V}, T_J = 150^\circ\text{C}$) | I_R | - | 30 2.5 50 | μA |
| Diode Capacitance ($V_R = 0 \text{ V}, f = 1.0 \text{ MHz}$) | C_D | - | 2.0 | pF |
| Forward Voltage ($I_F = 1.0 \text{ mA}$) ($I_F = 10 \text{ mA}$) ($I_F = 50 \text{ mA}$) ($I_F = 150 \text{ mA}$) | V_F | - | 715 855 1000 1250 | mV |
| Reverse Recovery Time ($I_F = I_R = 10 \text{ mA}, I_{R(REC)} = 1.0 \text{ mA}$) (Figure 1) $R_L = 100 \Omega$ | t_{rr} | - | 6.0 | ns |



- Notes: 1. A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 10 mA.
 2. Input pulse is adjusted so $I_{R(\text{peak})}$ is equal to 10 mA.
 3. $t_p \gg t_{rr}$

Figure 1. Recovery Time Equivalent Test Circuit

Curves Applicable to Each Cathode

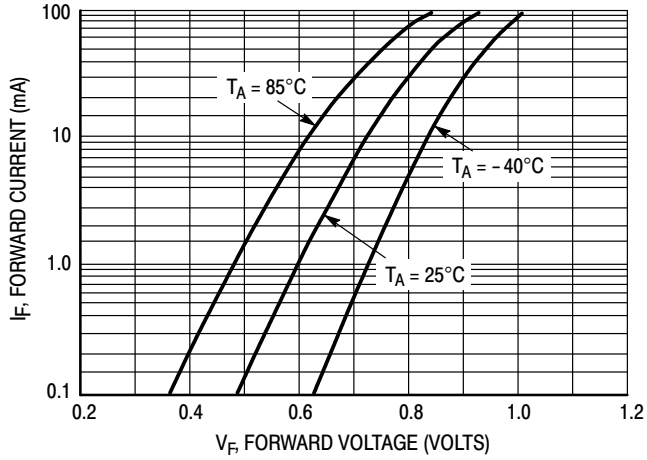


Figure 2. Forward Voltage

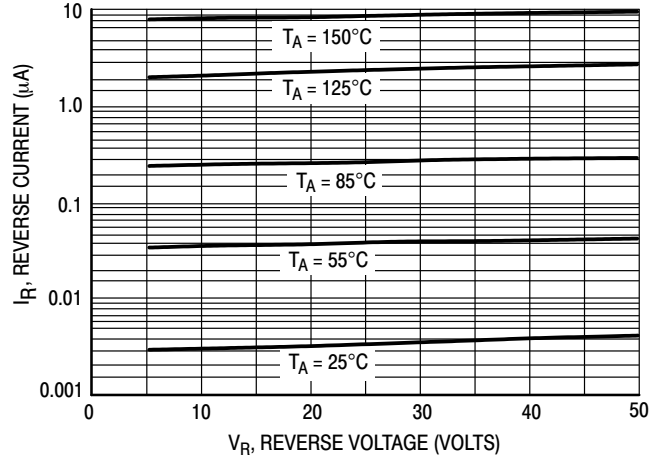


Figure 3. Leakage Current

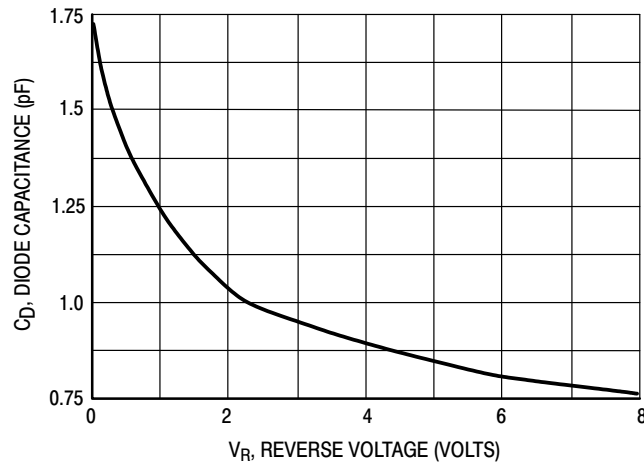


Figure 4. Capacitance

BAW56LT1G, SBAW56LT1G, BAW56LT3G, SBAW56LT3G, SSV1BAW56LT1G

PACKAGE DIMENSIONS

SOT-23 (TO-236)
CASE 318-08
ISSUE AP

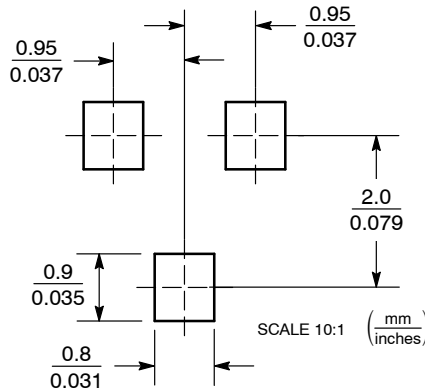


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

| DIM | MILLIMETERS | | | INCHES | | |
|-----|-------------|------|------|--------|-------|-------|
| | MIN | NOM | MAX | MIN | NOM | MAX |
| A | 0.89 | 1.00 | 1.11 | 0.035 | 0.040 | 0.044 |
| A1 | 0.01 | 0.06 | 0.10 | 0.001 | 0.002 | 0.004 |
| b | 0.37 | 0.44 | 0.50 | 0.015 | 0.018 | 0.020 |
| c | 0.09 | 0.13 | 0.18 | 0.003 | 0.005 | 0.007 |
| D | 2.80 | 2.90 | 3.04 | 0.110 | 0.114 | 0.120 |
| E | 1.20 | 1.30 | 1.40 | 0.047 | 0.051 | 0.055 |
| e | 1.78 | 1.90 | 2.04 | 0.070 | 0.075 | 0.081 |
| L | 0.10 | 0.20 | 0.30 | 0.004 | 0.008 | 0.012 |
| L1 | 0.35 | 0.54 | 0.69 | 0.014 | 0.021 | 0.029 |
| HE | 2.10 | 2.40 | 2.64 | 0.083 | 0.094 | 0.104 |
| θ | 0° | --- | 10° | 0° | --- | 10° |

STYLE 12:
PIN 1. CATHODE
2. CATHODE
3. ANODE

SOLDERING FOOTPRINT



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